

7E4051

Roll No. _____

Total No of Pages: 4**7E4051****B. Tech. VII Sem. (Back) Exam., Nov. – Dec. - 2018****Electronics & Communication Engineering****7EC6.3 (O) Operating System****Time: 3 Hours****Maximum Marks: 80****Min. Passing Marks: 26***Instructions to Candidates:*

*Attempt any **five** questions, selecting **one** question from **each** unit. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
(Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) Define Operating System. Explain how operating system acts as a resource manager? Differentiate between Multiprogramming and Multi-processing? [8]

(b) What is the difference between User level threads & Kernel level threads? Under what circumstance is one type better than the other? [8]

OR

Q.1 (a) What are the different services provided by the operating system? Explain all of them in detail. [8]

(b) What are the six major activities of an operating system with regards to file management? [8]

UNIT- II

Q.2 (a) What is a process? What is the difference between a program and a process?

Explain PCB using suitable example. [8]

(b) Define Scheduling criteria. Explain Quenching diagram for the CPU scheduling in detail. [8]

OR

Q.2 (a) In-connection with inter process communication explain the following: [8]

(i) Race condition

(ii) Critical condition

(iii) Sleep & Wake up

(iv) System call

(b) Consider the following set of processes with arrival time and CPU burst time given in ms. [8]

Process	Arrival time	Burst time
P ₁	0	8
P ₂	1	4
P ₃	2	9
P ₄	3	5

What is the average waiting time for these processes with pre-emptive SJF scheduling? [8]

UNIT- III

Q.3 Explain the Page – replacement algorithm. [16]

OR

Q.3 (a) What is the difference between Pager and Swapper? [4]

(b) What is demand paging? [4]

(c) What is thrashing? [4]

(d) Write short note on TLB. [4]

UNIT- IV

Q.4 (a) Explain various disk scheduling algorithm in brief. [8]

(b) What are the various access methods for file system? [8]

OR

Q.4 Explain the following:

(a) Tree structured directory [4]

(b) Spooling [4]

(c) File system mounting [4]

(d) Memory mapped files [4]

UNIT- V

Q.5 (a) What is deadlock? What are the necessary conditions for deadlock to occur? [8]

(b) Explain the following : [8]

(i) Resource allocation graph

(ii) Recovery from deadlock

OR

Q.5 (a) Explain the difference between internal & external fragmentation. [8]

(b) Explain the following : [8]

(i) Logical & Physical address space

(ii) Dynamic linking

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7E4047	Roll No. _____	Total No of Pages: 3
<p style="font-size: 18pt; font-weight: bold;">7E4047</p> <p style="font-size: 14pt; font-weight: bold;">B. Tech. VII Sem. (Back) Exam., Nov. – Dec. - 2018</p> <p style="font-size: 14pt; font-weight: bold;">Electronics & Communication Engineering</p> <p style="font-size: 14pt; font-weight: bold;">7EC4 (O) IC Technology</p>		

Time: 3 Hours **Maximum Marks: 80**
Min. Passing Marks: 26

Instructions to Candidates:
 Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.
 Units of quantities used/calculated must be stated clearly.
 Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)

1. NIL

2. NIL

UNIT- I

- Q.1 (a) Discuss various steps for wafer preparation from the Si ingot obtained after CZ or FZ Method. [6]
- (b) Explain the different kinds of crystal defects. [5]
- (c) In a CZ growth, if the density of solid silicon is $1.4 \times 10^{-3} \text{ gm/cm}^3$, thermal conductivity of solid is $7.6 \times 10^{-4} \text{ mho}$ and thermal gradient at the interface is 0.4, then find out the maximum pull rate. Assume the latent heat of fusion is 1.5J. [5]

OR

- Q.1 (a) What is Czochralski Growth? Differentiate between pull rate and growth rate. Can pull rate become negative? If yes, explain why? [6]

- (b) What do you understand by MGS and EGS? How is EGS obtained from MGS? [5]
- (c) Find the concentration of boron in crystal at a fraction solidified of 0.5, if C_s at $X=0.04$ is 2×10^{18} and segregation coefficient is 0.8. [5]

UNIT- II

- Q.2 (a) Write five specifications for electronic grade silicon. [4]
- (b) What are “charged defects”? What is their origin and how these affect the electronic performances? [4]
- (c) What do you mean by “solubility limit”? If we dissolve more than this limit, how it increases the defects? [4]
- (d) Compare Czochralski and Float zone refine method from the following points of view : [4]
- (i) Yield
 - (ii) Purity
 - (iii) Economic

OR

- Q.2 (a) Develop Fick's law of diffusion. Write their solutions for constant surface concentration and constant total dopant for constant diffusivities. Clearly state the boundary conditions for both cases. [8]
- (b) Explain the deal grove model of oxidation and discuss the effects of presence of water, sodium and halogens on oxidation. [8]

UNIT- III

Q.3 Explain the following in detail -

- (a) Chemical equilibrium and law of mass action. [8]
- (b) Low pressure CVD of dielectric and semiconductor. [8]

OR

Q.3 Discuss Vapour phase epitaxy and Molecular beam epitaxy. [16]

UNIT- IV

Q.4 Explain photo lithography and proximity printers with suitable diagram. [16]

OR

Q.4 Write notes on types of etching. [16]

UNIT- V

Q.5 Write short note on the following -

- (a) LOCOS Methods [8]
- (b) Trench Isolation [8]

OR

Q.5 Write short note on the following -

- (a) Metallization [8]
- (b) Planarization [8]

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Total No of Pages: **3****7E4048****7E4048**

B. Tech. VII Sem. (Back) Exam., Nov. – Dec. - 2018
Electronics & Communication Engineering
7EC5 (O) VLSI Design

Time: 3 Hours

Maximum Marks: 80
Min. Passing Marks: 26

Instructions to Candidates:

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) Draw the different fabrication step of n-well CMOS? [8]

(b) Derive the V-I characteristics of enhancement MOSFET- [8]

(i) For ohmic Region

(ii) For saturation Region

OR

Q.1 (a) How the V-I characteristic modify with channel length modulation effect? Show its a V-I characteristics and V-I relation. [8]

(b) Draw the transfer conductance characteristic of - [8]

(i) NMOS depletion mode MOSFET

(ii) PMOS enhancement mode MOSFET

UNIT- II

- Q.2 (a) How the threshold voltage V_{T0} depends on- [8]
- (i) V_{DS}
 - (ii) V_{SB}
- (b) If channel width $W = 8 \mu\text{m}$, Channel length $\ell = 0.5 \mu\text{m}$ and is made in a process where process conductivity is $180 \mu\text{A/V}^2$, $V_{th} = 0.7\text{V}$ and $V_{DD} = 3.3\text{V}$, find The Linearized resistance. [8]

OR

- Q.2 (a) What is Noise margin? Explain the procedure to determine noise margin. [8]
- (b) What is Body Effect? [8]

UNIT- III

- Q.3 (a) Explain power dissipation in the CMOS logic circuit. [8]
- (b) Draw two input multiplexer circuit using transmission gate. [8]

OR

- Q.3 (a) Explain gate delay for depletion mode inverter. [8]
- (b) Provide CMOS logic structure at transistor level for the function: [8]

$$F = \overline{A \cdot (B + C) + D \cdot E}$$

UNIT- IV

- Q.4 Draw the stick diagram layout for:
- (a) 2 – input CMOS NAND gate [8]
 - (b) 2 – input CMOS NOR gate [8]

OR

Q.4 (a) Draw the physical layout for [8]

$$X = \overline{ab + cd}$$

(b) Write a short note on layout optimization? [8]

UNIT- V

Q.5 Write a VHDL code on:

(a) D flip – flop [4]

(b) T flip - flop [4]

(c) J – K flip - flop [4]

(d) S – R flip - flop [4]

OR

Q.5 Write VHDL code for-

(a) 4 – bit adder using full adder [8]

(b) 8:1 MUX [8]

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Total No of Pages: **3****7E7081**

B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018
Electronics & Communication Engineering
7EC1A Antenna & Wave Propagation

Time: 3 Hours

Maximum Marks: 80
Min. Passing Marks: 26

Instructions to Candidates:

*Attempt any **five** questions, selecting **one** question from **each** unit. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) Explain the following terms – [8]

- (i) Polarization
- (ii) Antenna Temperature
- (iii) Isotropic Radiator
- (iv) Gain of an Antenna

(b) Derive an expression of Radiated power and Radiation Resistance of a Hertzian dipole. [8]

OR

Q.1 (a) Describe the Beam width and Directivity of an Antenna. [8]

(b) A thin dipole antenna is $\frac{t}{15}$ long. If its loss resistance is 1.5Ω , find radiation resistance and efficiency. [8]

UNIT- II

- Q.2 (a) Calculate the field strength of a uniform linear array. [8]
- (b) What is multiplication of patterns? Example with suitable examples. [8]

OR

- Q.2 (a) Prove that the directivity of an end-Fire array of the point source spaced at a distance apart is given by – [8]

$$D(\theta) = \frac{2}{1 + \frac{\sin 2\beta d}{2\beta d}}$$

- (b) If the phase difference $\delta = -90^\circ$, A uniform linear array consists of 16 isotropic point sources with a spacing of $\frac{\lambda}{4}$, calculate: [8]
- (i) Directivity
- (ii) Effective aperture

UNIT- III

- Q.3 (a) Write short notes on Yagi – Uda antenna and Helical antenna. [8]
- (b) Briefly explain Microstrip patch antenna and reflector antenna. [8]

OR

- Q.3 (a) Explain the method of Antenna Radiation Pattern measurements. [8]
- (b) Explain the working of a folded dipole antenna. [4]
- (c) What are the different types of antennas used at very high frequencies? [4]

UNIT- IV

- Q.4 (a) Explain the mechanism of Radio wave propagation. [8]
- (b) What do you understand by Duct propagation? How are ducts formed? What are its merits and demerits? [8]

OR

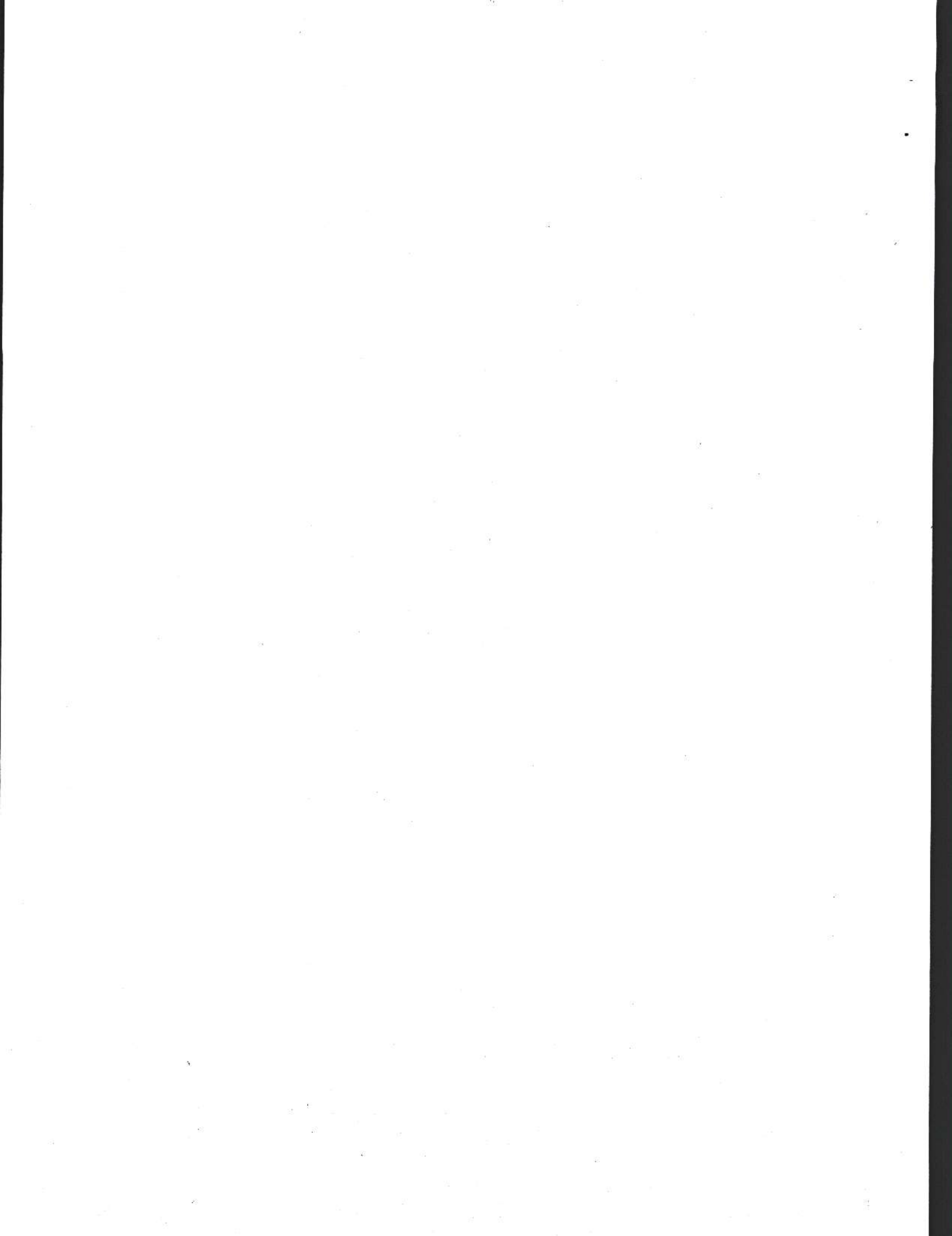
- Q.4 (a) What is Tropospheric scattering? What are the frequency range for it? [4]
- (b) What are the factors affecting space wave field strength? [4]
- (c) Derive an expression of field strength due to space wave. [8]

UNIT- V

- Q.5 (a) Derive the expression for the Refractive Index of the Ionosphere. [8]
- (b) Discuss the characteristics of different ionosphere layers in brief. [8]

OR

- Q.5 (a) Explain the effect of Faraday rotation and Earth's magnetic field on Ionospheric wave propagation. [8]
- (b) Explain the following in brief – [8]
- (i) Skip distance
 - (ii) MUF
 - (iii) Virtual height
 - (iv) Critical Frequency



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B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. – 2018
Electronic Instrumentation & Control Engineering
7EI3A Digital Image Processing
Common with EC, EIC

Time: 3 Hours**Maximum Marks: 80****Min. Passing Marks: 26***Instructions to Candidates:*

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) Explain Image sensing and Acquisition. [8]

(b) What do you mean by Image registration? Describe briefly. [8]

OR

Q.1 What is Colour model or Colour system? Explain RGB, CMY and HSI colour model. [16]

UNIT- II

Q.2 (a) Explain Image smoothing using frequency domain fitters. [8]

(b) What is Spatial Filtering? Define spatial correlation and convolution with an example. [8]

OR

- Q.2 (a) What is Image Sharpening? Explain first and second order derivatives of image sharpening? [10]
- (b) Explain Histogram equalization of an image. [6]

UNIT- III

Q.3 Write a short note on –

- (a) Inverse filtering [8]
- (b) Wiener filtering [8]

OR

- Q.3 (a) Explain Image Degradation / Restoration Model in brief. [8]
- (b) Explain Erlong (Gamma) Noise and Rayleigh Noise. [8]

UNIT- IV

Q.4 Write a short note on –

- (a) Erosion [8]
- (b) Dilation [8]

OR

- Q.4 (a) What do you mean by gray scale Morphology? [8]
- (b) What is Thinning and Pruning? Explain briefly. [8]

UNIT- V

- Q.5 (a) What is Watersheds Transformation and construction of Watershed line or Dams? [12]
- (b) What do you mean by Image Thresholding? [4]

OR

- Q.5 (a) Explain briefly loss – less predictive image compression Technique/ Coding. [12]
- (b) Explain basic Image segmentation operations. [4]
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7E7083

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Total No of Pages: **3****7E7083****B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018****Electronics & Communication Engineering****7EC4A Wireless Communication****Time: 3 Hours****Maximum Marks: 80****Min. Passing Marks: 26***Instructions to Candidates:*

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
(Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) Explain the DSSS with binary phase shift keying and compare its performance with FHSS. [8]

(b) What do you mean by Code division multiplexing? [8]

OR

Q.1 Write short note on -

(a) FHSS signals [8]

(b) Spreading Codes [8]

UNIT- II

- Q.2 (a) What is Link engineering? Explain different types of link used in communication system. [8]
- (b) Explain the concept of diffraction loss as a function of path difference around an obstruction by Fresnel zones. [8]

OR

- Q.2 (a) What is Multipath fading? Explain various fading channels present. [8]
- (b) Explain the transmitter and receiver block diagram of microwave link. [8]

UNIT- III

- Q.3 (a) Explain the CDMA principle of operation with its advantages and disadvantages. Which type of Handoffs occur in CDMA mobile system? [10]
- (b) If a normal GSM time slot consists of 6 trailing bits, 8.25 guard bits, 26 training bits and 2 traffic bursts of 61 bits of data, find the frame efficiency. [6]

OR

- Q.3 (a) The “near – far interference” is a serious problem in wireless cellular CDMA network, what is the reason for it? [8]
- (b) Explain the TDMA principle of operation with TDMA/TDD example, also write its advantages, disadvantages and efficiency. [8]

UNIT- IV

- Q.4 (a) Explain the Process of Speech Coding in GSM. [8]
- (b) Write short note on - [4×2=8]
- (i) Mobile IP
- (ii) Broad band wireless 1002.16

OR

- Q.4 (a) Explain the operation of DECT with its network architecture. [8]
- (b) Write short note on – [4×2=8]
- (i) Zig bee
- (ii) RFID Technology

UNIT- V

- Q.5 (a) Explain the AOCS and TTC with suitable diagram for a satellite. [8]
- (b) Define Satellite access. Describe the difference between single and multiple access. [8]

OR

- Q.5 (a) List the main components of an earth station transmitter. With the assistance of a block diagram briefly explain its function of operation. [8]
- (b) Write short note on –
- (i) Orbital period and Velocity [4]
- (ii) High power amplifier [4]
-

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Total No of Pages: 3

7E7084

B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018
Electronics & Communication Engineering
7EC5A VLSI Design

Time: 3 Hours

Maximum Marks: 80
Min. Passing Marks: 26

Instructions to Candidates:

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

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*Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) What are different kinds of MOS transistors? Explain the structure and operation of MOS transistor. [8]

(b) The process parameters for an NMOS are - [8]

Oxide thickness = 500 Å, Substrate doping $M_A = 10^{16}/\text{cm}^3$, Polysilicon gate doping $M_D = 10^{20}/\text{cm}^3$, Oxide interface fixed charge density = $2 \times 10^{10}/\text{cm}^3$.

Calculate the threshold voltage V_T .

OR

Q.1 (a) What are the different techniques of CMOS transistor fabrication? Explain one in detail. [8]

(b) Explain "Depletion mode MOSFET". [8]

UNIT- II

- Q.2 (a) Write short note on – [8]
- (i) Noise Margins
 - (ii) Pull-up to pull – down ratio for an NMOS inverter.
- (b) Design a resistive load inverter with $R = 1k\Omega$ such that at $V_{OL} = 0.6V$. The enhancement type NMOS driver transistor has following parameters :
- $V_{DD} = 5V, V_T = 1V, \mu_n.C_{ox} = 22\mu A/V^2$ – [8]
- (i) Determine the aspect ratio
 - (ii) Determine Noise margins NM_L and NM_H .

OR

- Q.2 (a) Derive β_n/β_p ratio of CMOS inverter. [10]
- (b) The NMOS device with $V_t = 0.7V$ has its source terminal grounded and a 1.3V is applied to gate. The device has $\mu_n.C_{ox} = 100 mA/V^2$, $W = 10mm$, $L = 1mm$. Find the value of drain current for $V_D = 3V$. [6]

UNIT- III

- Q.3 (a) Realize the following expression using CMOS inverter – [8]
- (i) $AB + \overline{A} \overline{B}$
 - (ii) $\overline{A + BC + DE}$
 - (iii) $AB + BC + AC$
 - (iv) $A \odot B$
- (b) What are DRC rules for layout? State any six DRC rules. [8]

OR

- Q.3 (a) Draw the layout using Euler path for $y = \overline{(A + BC)(D + E)}$. [8]
- (b) Draw latch – up formation in CMOS inverter. [8]

UNIT- IV

- Q.4 (a) What is C² MOS logic? Draw logic circuit using it. What are advantages of such logic? [8]
- (b) Explain the working of SRAM cell and DRAM cell. [8]

OR

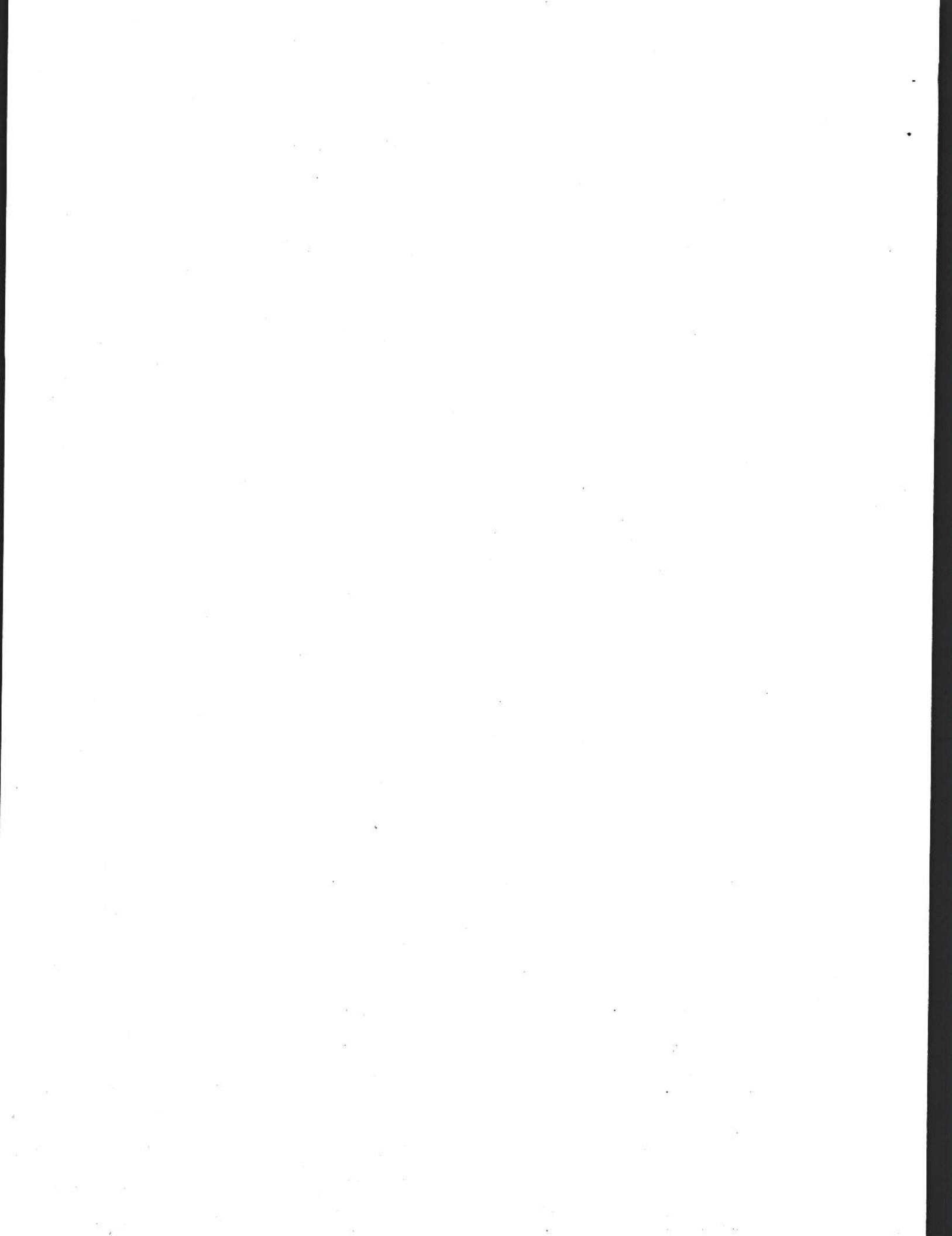
- Q.4 (a) Explain pre – charge and evaluation logic. [8]
- (b) Draw $y = \overline{(AB + C)}$ using Domino logic. [8]

UNIT- V

- Q.5 (a) Write VHDL Code for S – R flip flop and D-flip flop. [10]
- (b) List the advantages and limitations of VHDL. [6]

OR

- Q.5 (a) Write the difference between FPGA and custom design. [8]
- (b) Write the difference between first and back end design. [8]



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Total No of Pages: **3**

7E7085

B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018
Electronic Instrumentation & Control Engineering
7EI6.2A/7EC6.1A Advanced Microprocessors
Common with EC, EIC

Time: 3 Hours

Maximum Marks: 80

Min. Passing Marks: 26

Instructions to Candidates:

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

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(Mentioned in form No. 205)*

1. NIL

2. NIL

UNIT- I

Q.1 (a) Explain the architecture of 8086 with the help of diagram. [8]

(b) List out various flag register bits and their description. [8]

OR

Q.1 (a) Construct minimum mode and maximum mode operation in 8086. [8]

(b) Explain system Bus Timing, and execution of program concept for 8086. [8]

UNIT- II

Q.2 What do you understand by addressing mode? Explain different addressing modes with suitable example for 8086 microprocessor. [16]

OR

Q.2 (a) Explain with example - [8]

(i) Strings

(ii) Procedures and Macros

(b) Explain Assembler Directives and operators. [8]

UNIT- III

Q.3 Explain various programming mode of 8279 keyboard and display controller. Also draw a block diagram showing its interfacing with microprocessor. [16]

OR

Q.3 Write short note on -

(a) RS – 232 [5]

(b) IEEE – 488 [5]

(c) 8086 based process control system [6]

UNIT- IV

Q.4 (a) Explain memory interfacing and decoding. [8]

(b) Explain DMA controller. [8]

OR

Q.4 (a) Explain interfacing microprocessor to keyboard and alpha numeric displays. [10]

(b) Compare static memory and dynamic memory. [6]

UNIT- V

- Q.5 (a) Explain multi user operating system concepts. [8]
- (b) Explain 8086 based multiprocessor systems. [8]

OR

Q.5 Write short note on -

- (a) 286 processors [4]
- (b) 386 processors [4]
- (c) 486 processors [4]
- (d) Pentium processors [4]

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Total No of Pages: 3**7E7086****7E7086**

B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. – 2018
Electronics & Communication Engineering
7EC6.3A VHDL

Time: 3 Hours

Maximum Marks: 80
Min. Passing Marks: 26

Instructions to Candidates:

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

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Use of following supporting material is permitted during examination.
(Mentioned in form No. 205)

1. NIL2. NIL

UNIT- I

- Q.1 (a) Describe the programming structure of VHDL and also explain Functional Simulation. [8]
- (b) Describe the Behavioral & Structural style of modeling with suitable example. [8]

OR

Q.1 Write a VHDL code for -

- (a) D – Latch. [4]
- (b) Half adder [4]
- (c) 4×1 MUX [4]
- (d) 3 - input NAND gate [4]

UNIT- II

- Q.2 (a) Explain Sequential statements with example. [8]
- (b) VHDL Description of structure with suitable example? [8]

OR

- Q.2 (a) Given the following function $f = ab + cd$. Write an entity declaration and alternative architectures for a system that computes the function. [8]
- (b) Explain Model Organization with example. [4]
- (c) What is NULL Transactions? Explain. [4]

UNIT- III

- Q.3 (a) Consider the function: $y = \overline{x_1} \overline{x_3} + x_2 \overline{x_3} + \overline{x_1} x_2$. Use the truth table to derive a circuit for y that uses a 2 – to – 1 MUX. [8]
- (b) Write a VHDL Code that specifies the barrel shifter circuit. [8]

OR

- Q.3 (a) Explain in brief Binary encoder & Binary decoder and explain Sensitivity list. [8]
- (b) Write a VHDL Code for a BCD – to – 7 Segment Code converter using a select signal assignment. [8]

UNIT- IV

- Q.4 (a) Write a VHDL Code of Serial Adder and also explain one hot encoding. [8]
- (b) Write short note on Mealy type FSM with example. [8]

OR

- Q.4 (a) Write down short note on Vending Machine with example. [8]
- (b) Write down VHDL Code for Moore type FSM and also explain Mealy type finite state machine. [8]

UNIT- V

- Q.5 (a) How many 16K memories can be placed (without over lapping) in the memory space of a processor that has 24 address lines? [8]
- (b) Using Logic gates, design an active low chip select for the memory device described in each of the following situations. [8]

OR

- Q.5 (a) Explain SRAM in brief and what is Clock skew and how it can be minimized? [8]
- (b) Write a VHDL Code for Sorting operation and Multiplier. [8]

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B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018
Electronic Instrumentation & Control Engineering
7E11A Neural Networks and Fuzzy Logic Control

Time: 3 Hours**Maximum Marks: 80****Min. Passing Marks: 26***Instructions to Candidates:*

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

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*Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)*

1. NIL _____2. NIL _____**UNIT- I**

Q.1 Explain the followings -

(a) Neurophysiology [8]

(b) Difference between biological neural network and artificial neural network. [8]

OR

Q.1 (a) Explain the McCulloch-Pitts model? [8]

(b) Explain the limitations of single layered neural network. [8]

UNIT- II

Q.2 Explain the “Adaline” in detail. [16]

OR

Q.2 Explain the followings -

(a) Back propagation learning Law [8]

(b) Supervised learning [8]

UNIT- III

Q.3 Explain all features of Membership functions. [16]

OR

Q.3 Explain the followings –

(a) Uncertainty and precision [8]

(b) Maximum membership principal [8]

UNIT- IV

Q.4 Explain all the Defuzzification methods in detail with suitable examples. [16]

OR

Q.4 Explain the followings –

(a) Graphical techniques of reference [8]

(b) Neural languages, Linguistic Hedges and rule based system [8]

UNIT- V

Q.5 Explain the General Fuzzy logic controller with a neat sketch and suitable examples. [16]

OR

Q.5 Explain –

(a) Fuzzy MIMO system [8]

(b) Fuzzy statistical process control [8]

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Roll No. _____

Total No of Pages: 4**7E7072****7E7072****B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018****Electronics & Communication Engineering****7E12A Digital Signal Processing****Common with AI, EC, EIC****Time: 3 Hours****Maximum Marks: 80****Min. Passing Marks: 26***Instructions to Candidates:*

*Attempt any **five** questions, selecting **one** question from **each** unit. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
(Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

Q.1 (a) Determine the Nyquist rate & Nyquist interval for the following signal –

$$x(t) = \frac{1}{\pi t} \sin(600\pi t) \quad [6]$$

(b) Draw block diagram of continuous time processing of discrete time signals and

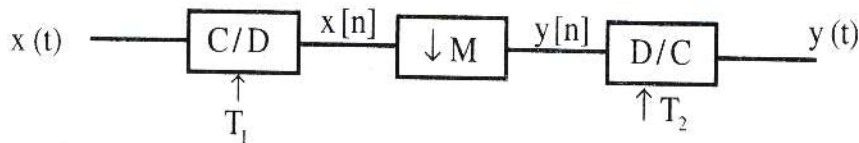
write mathematical expression in term of time domain and frequency domain for

output of each stage. [10]

OR

Q.1 Consider the system in figure –

[16]



Assume that the input is band limited :

$$x_c(j\omega) = 0 \text{ for } |\omega| > 2\pi \cdot 1000$$

- (a) What constraint must be placed on M, T_1 & T_2 in order for $y_a(t)$ to be equal to $x_a(t)$?
- (b) If $f_1 = f_2 = 20 \text{ KHz}$ & $M = 4$, find the expression for $y_a(t)$ in terms of $x_a(t)$.

UNIT- II

Q.2 (a) Determine the homogeneous solution of the system, described by – [8]

$$y(n) - 3y(n-1) - 4y(n-2) = x(n)$$

- (b) $H(z) = \frac{1+3z^{-1}}{1+\frac{1}{2}z^{-1}}$, write an expression of inverse system of $H(z)$. [8]

OR

Q.2 (a) Define Minimum – phase system, write –

- (i) Generalized expression of minimum – phase. [4]
- (ii) Discuss stability and causality condition for a discrete system. [4]

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(b) Write short notes on the following –

(i) All – pass system [4]

(ii) Frequency response of LTI system [4]

UNIT- III

Q.3 (a) Obtain direct form I and II realization of a system described by – [10]

$$y(n) - \frac{3}{4}y(n-1) + \frac{1}{8}y(n-2) = x(n) + \frac{1}{2}x(n-1)$$

(b) Realize the system with difference equation – [6]

$$y(n) = \frac{3}{4}y(n-1) - \frac{1}{8}y(n-2) + x(n) + \frac{1}{3}x(n-1)$$

in cascade form.

OR

Q.3 (a) Draw the cascades and parallel realizations for the following system functions - [10]

$$H(z) = \frac{1 + \frac{1}{4}z^{-1}}{\left(1 + \frac{1}{2}z^{-1}\right)\left(1 + \frac{1}{2}z^{-1} + \frac{1}{4}z^{-2}\right)}$$

(b) Explain the FIR system and Transposed form. [6]

UNIT- IV

Q.4 Design an FIR linear phase filter using Kaiser Window to meet the following specification – [16]

$$0.99 \leq |H(e^{jw})| \leq 1.01, \text{ for } 0 \leq |w| \leq 0.19\pi$$

$$|H(e^{jw})| \leq 0.01, \text{ for } 0.21\pi \leq |w| \leq \pi$$

OR

Q.4 Write short notes on the following –

(a) Bilinear transformation

[8]

(b) Impulse invariance transformation

[8]

UNIT- V

Q.5 Explain the following –

(a) Decimation in Time FFT Algorithm

[10]

(b) Properties of the DFT

[6]

OR

Q.5 Determine the four point DFT of the sequence $x(n) = (1, 0, 2, 1)$ using DIT Algorithm.

[16]

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7E7073	Roll No. _____	Total No of Pages: 2
<p style="font-weight: bold; font-size: 1.2em;">7E7073</p> <p style="font-weight: bold;">B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018</p> <p style="font-weight: bold;">Electronic Instrumentation & Control Engineering</p> <p style="font-weight: bold;">7E14A Analytical & Environmental Instrumentation</p>		

Time: 3 Hours

Maximum Marks: 80
Min. Passing Marks: 26

Instructions to Candidates:

*Attempt any **five questions**, selecting **one question** from **each unit**. All questions carry **equal marks**. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

Use of following supporting material is permitted during examination. (Mentioned in form No. 205)

1. NIL _____

2. NIL _____

UNIT- I

- Q.1 (a) Explain the principle of atomic absorption spectrophotometer. Discuss its working with functional block diagram. [3+5=8]
- (b) How mass spectroscopy is different from optical spectroscopy. Describe the components of a mass spectrometer. [3+5=8]

OR

- Q.1 (a) Explain the principle of fluorescence spectroscopy. Discuss the working of a double beam fluorimeter with a schematic diagram. [3+5=8]
- (b) Discuss the following with reference to X-ray spectrometry: [2×4=8]
- (i) X-ray generation
 - (ii) Collimator
 - (iii) Monochromators
 - (iv) Detectors.

UNIT- II

- Q.2 (a) Discuss the working principle of conventional infrared gas analyzers. List its drawbacks and how these are overcome in improved infrared gas analyzer. [5+3=8]

- (b) Explain the working of thermal conductivity gas analyzers and discuss working of hot wire thermal conductivity gas analyzer. [3+5=8]

OR

- Q.2 (a) Discuss a scheme for measurement of CO₂ in flowing beverage used infrared gas analyzers. [8]
 (b) Explain the working of chemiluminescent ozone analyzer with a functional block diagram. [8]

UNIT- III

- Q.3 (a) Explain the working principle of Gas chromatograph. Discuss the applications. [8]
 (b) Explain the working of high pressure liquid chromatography with schematic diagram. [8]

OR

- Q.3 (a) Discuss the working of any two detectors used in gas chromatographs. [8]
 (b) Discuss with reference to liquid chromatography.
 (i) Sample injection system [4]
 (ii) Detection system [4]

UNIT- IV

- Q.4 (a) What are the major effects of the Sulphur oxide pollutants? Discuss a conductivity method of measurement of SO₂ in air. [3+5=8]
 (b) How Nitrogen oxides affects the environment. Explain the measurement technique of nitrogen oxides using CO Laser. [3+5=8]

OR

- Q.4 (a) Discuss the working principle of measurement of hydrocarbons by flame ionization detection technique. [8]
 (b) Explain the following:-
 (i) Smoke monitor [4]
 (ii) Visible emission monitoring system [4]

UNIT- V

- Q.5 (a) What is pH? Explain the principle of pH measurement. [3+5=8]
 (b) What is meant by ion selective electrodes? Discuss its types, merits and de-merits. [3+5=8]

OR

- Q.5 (a) Explain the basic principle of conductivity meters. Discuss the measurement of conductance by Null method. [3+5=8].
 (b) Explain the working principle of analyzer for measurement of dissolved oxygen. [8]

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7E7074

Roll No. _____

Total No of Pages: 2**7E7074**

B. Tech. VII Sem. (Main / Back) Exam., Nov. – Dec. - 2018
Electronic Instrumentation & Control Engineering
7E15A Instrumentation in Industries

Time: 3 Hours**Maximum Marks: 80****Min. Passing Marks: 26***Instructions to Candidates:*

*Attempt any **five** questions, selecting **one** question from **each** unit. All questions carry **equal** marks. Schematic diagrams must be shown wherever necessary. Any data you feel missing suitably be assumed and stated clearly.*

Units of quantities used/calculated must be stated clearly.

*Use of following supporting material is permitted during examination.
 (Mentioned in form No. 205)*

1. NIL2. NIL**UNIT- I**

- Q.1 (a) Draw and explain the man power distribution curve for process industries. [8]
 (b) Explain instrument department functions and responsibilities with the help of organizational chart in process plant instrumentation. [8]

OR

- Q.1 (a) What are the various control panels and displays are used in process industries? Explain in brief. [8]
 (b) Why power plant training is useful for instrumentation engineer? Discuss about the major areas of power plant training for process Industries. [8]

UNIT- II

- Q.2 (a) Draw and explain the C & I diagram of cascade temperature control with heating & cooling capability. [8]
 (b) Draw and explain the C & I diagram of Reactor pressure control by throttling flow of vent gas. [8]

OR

- Q.2 (a) Explain the control schemes of Reactor pressure control by modulating gas make up. [8]
- (b) Discuss about the C & I of Reactor temperature control with recirculation. [8]

UNIT- III

- Q.3 (a) Explain the control schemes of steam trap replaced by level control. [8]
- (b) Explain the C & I of Temperature pressure cascade control loop on steam heater. [8]

OR

- Q.3 Explain the following –
- (a) Condenser control by changing the wetted surface area. [8]
- (b) Hot gas by pass control of Heat exchangers. [8]

UNIT- IV

- Q.4 (a) Explain the principles and classification of dryers with neat sketches. [8]
- (b) Explain the C & I diagram of forced circulation type evaporators with merits & demerits. [8]

OR

- Q.4 Explain the following C & I diagrams –
- (a) C & I of throttling control of rotary pumps. [8]
- (b) Heated cylinder type dryer control schemes. [8]

UNIT- V

- Q.5 (a) Explain the instrumentation & control schemes of feed water control for a boiler. Also, explain safety interlocks associated with it. [8]
- (b) What are the selection criteria of instrumentation for steam power plants? Explain the different factors consideration for designing the control room of steam power plants. [8]

OR

- Q.5 Write short notes on –
- (a) Data logging & computing equipments in steam power plants. [8]
- (b) Air – Fuel ratio control in combustion unit of power plants. [8]